

**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) An apparatus for metal electroplating, comprising:  
~~a electroplating an electroplating tank for containing an electrolyte at a first temperature;~~  
~~a substrate holder for holding a semiconductor substrate; and~~  
~~a heater for heating the portion of the electrolyte adjacent to the substrate holder to a second temperature higher than the first temperature,~~  
~~wherein the heater comprises two individual thermal insulating supports respectively having a heating element thereon and an opening formed between the two insulating supports for allowing the electrolyte to flow therethrough, and~~  
wherein the heater is independently disposed in the electroplating tank and in a position opposite to the substrate holder, and the heater provides no fluid into the electroplating tank.
  
- 2-3. (Cancelled)
  
4. (Original) The apparatus as claimed in claim 1, wherein a temperature difference of about 5 to 60 °C exists between the second temperature and the first temperature.
  
5. (Original) The apparatus as claimed in claim 1, wherein the second temperature is about 27 to 80 °C.
  
6. (Original) The apparatus as claimed in claim 1, wherein the electrolyte comprises Cu ions.

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7-23. (Cancelled)